

method to be described later and the electrode layer 132 is prevented from extending beyond the insensitive region and from narrowing the area of the magnetoresistive-effect device capable of detecting the magnetic field.

[0458] Referring to FIG. 21, the width dimension T63 of the electrode layer 132 extending over the insensitive region D of the multilayer film 201 is preferably within a range from 0  $\mu\text{m}$  to 0.08  $\mu\text{m}$ . The width dimension T63 of the electrode layer 132 is more preferably within a range of 0.05  $\mu\text{m}$  to 0.08  $\mu\text{m}$ .

[0459] Referring to FIG. 21, the magnetic coupling junction M between the multilayer film 201 and each of the hard bias layers 89 and 89 is fabricated of an interface with the end face of only the first free magnetic layer 85, of both the first free magnetic layer 85 and the second free magnetic layer 87.

[0460] By producing the magnetoresistive-effect device of FIG. 21 through the manufacturing method to be described later, the side face of the multilayer film 201 and the side face of the insulator layer 133 are set to be parallel to each other.

[0461] FIG. 22 is a cross-sectional view of the magnetoresistive device of a seventeenth embodiment of the present invention, viewed from an ABS side thereof.

[0462] The magnetoresistive-effect device shown in FIG. 22 includes, on the multilayer film 202 having the same construction as the one in the magnetoresistive-effect device shown in FIG. 12, a laminated insulator layer 135 constructed of  $\text{Al}_2\text{O}_3$ , and electrode layers 134 and 134 with their end faces 134a and 134a in direct contact with both sides of the insulator layer 135.

[0463] The construction and materials of the layers of the multilayer film 202 remain the same as those of the magnetoresistive-effect device shown in FIG. 12. Referring to FIG. 22, however, no protective layer 15 is deposited on top of the multilayer film 202.

[0464] The metallic layers 88 and 88, the hard bias layers 89 and 89 and the intermediate layers 90 and 90 deposited on the substrate 10 are identical, in construction and material, to the counterparts in the magnetoresistive-effect device shown in FIG. 12.

[0465] The first pinned magnetic layer 81 and the second pinned magnetic layer 83 are in a ferrimagnetic state with the magnetization directions thereof being antiparallel. The first pinned magnetic layer 81 and the second pinned magnetic layer 83 pin each other in magnetization direction, thereby stabilizing the magnetization direction of the pinned magnetic layer P in one direction as a whole.

[0466] In the magnetoresistive-effect device shown in FIG. 22, the first free magnetic layer 85 and the second free magnetic layer 87, having different magnetic moments and in a ferrimagnetic state with the magnetization directions thereof being antiparallel, are laminated with the nonmagnetic material layer 86 interposed therebetween, and function as a single free magnetic layer F.

[0467] The two end portions of the free magnetic layer F, having disturbed magnetization directions, present a poor reproduction gain, and become insensitive regions unable to exhibit no substantial magnetoresistive effect.

[0468] In the seventeenth embodiment again, the sensitive region E and the insensitive regions D and D of the multilayer film 202 are measured using the micro track profile method. Referring to FIG. 22, the portion, having the width dimension T64, of the multilayer film 202 is the sensitive region E, and the portions, each having the width dimension T65, on both sides of the sensitive region E are the insensitive regions D and D.

[0469] In the sensitive region E, the magnetization direction of the pinned magnetic layer P is pinned correctly in a direction parallel to the Y direction, and the magnetization direction of the free magnetic layer F is correctly aligned in the X direction. The pinned magnetic layer P and the free magnetic layer F are thus perpendicular in magnetization direction. The magnetization of the free magnetic layer F varies sensitively in response to an external magnetic field from the recording medium. An electrical resistance varies in accordance with the relationship between the variation in the magnetization direction of the free magnetic layer F and the pinned magnetic field of the pinned magnetic layer P. A leakage magnetic field from the recording medium is thus detected in response to a variation in voltage due to the electrical resistance variation.

[0470] The electrode layers 134 and 134 deposited above the multilayer film 202 extend over the multilayer film 202. The width dimension of the top surface of the multilayer film 202 not covered with the electrode layers 134 and 134 is the optical read track width O-Tw.

[0471] The magnetic read track width M-Tw, determined by the width dimension of the sensitive region E not covered with the electrode layers 134 and 134, is a width dimension T64, which is also the dimension of the sensitive region E.

[0472] In the seventeenth embodiment, the electrode layers 134 and 134 formed on the multilayer film 202 fully cover the insensitive regions D and D, setting the optical read track width O-Tw and the magnetic read track width M-Tw (i.e., the width dimension of the sensitive region E) to approximately the same dimension.

[0473] It is not a requirement that the electrode layers 134 and 134 formed above the multilayer film 202 fully cover the insensitive regions D and D, and the electrode layer 134 may be narrower than the insensitive region D. In this case, the optical read track width O-Tw becomes larger than the magnetic read track width M-Tw.

[0474] The percentage of the sense current flowing from the electrodes 134 and 134 to the multilayer film 202 without passing through the hard bias layers 89 and 89 is increased.

[0475] The electrode layers 134 and 134, extending over the insensitive regions D and D, prevent the sense current from flowing into the insensitive regions D and d, thereby controlling the generation of noise.

[0476] Referring to FIG. 22, the protective layer 15 is not deposited on top of the multilayer film 202, and the insulator layer 135 is directly deposited on the antiferromagnetic layer 80. The insulator layer 135 also serves as an antioxidizing protective layer. The electrode layers 134 and 134 are directly in contact with the antiferromagnetic layer 80.

[0477] This arrangement presents a smaller electrical resistance than the arrangement in which the electrode layers